

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

Generic Copy

26-JUL-2005

SUBJECT: ON Semiconductor Final Product/Process Change Notification #14238

TITLE: Transfer of Analog Bipolar Integrated Circuits Die Manufacturing from East Greenwich (USA) to Roznov (Czech Republic)

EFFECTIVE DATE: 26-Sep-2005

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Fab Site

AFFECTED PRODUCT DIVISION(S): Analog Products

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Bob Marquis <FC88FC@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or Patrick Rousset <TTT252@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is the last Final PCN for Initial PCN#13298, in addition to the FPCN#13517 from July 2004, FPCN#13823 from November 2004, FPCN#13889 from January 2005, FPCN#13939 from March 2005, FPCN14075 from May 2005 & FPCN#14131 from June 2005.

This notice is to confirm the qualification and transfer of integrated circuits processed with the 50 Volt, 40 Volt, 30 Volt, 17 Volt and 14 Volt technologies from the ON Semiconductor East Greenwich facility in Rhode Island (USA) to the Tesla wafer fab located in Roznov, Czech Republic due to the shutdown of the EG facility as previously announced.

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The integrated circuits design, electrical specifications, and mask sets remain identical. A full electrical characterization over the operating temperature range has been performed for each product to check the device functionality and electrical specifications.

Qualification tests results show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards. ON Semiconductor recommends that customers evaluate sample units in each associated application circuit to ensure there are no unexpected electrical incompatibilities.

RELIABILITY DATA SUMMARY:

| Test | Conditions | Duration | Lots | Results |
|----------------------|---------------------|-------------|---------|---------|
| | | | | |
| Early Life (ELFR) | Ta=+125 deg C, Bias | 48hrs | 13 lots | 0/12800 |
| High Temp. Operating | Ta=+125 deg C, Bias | 1008hrs | 46 lots | 0/3617 |
| Life (HTOL) | | | | |
| Temp. Cycle (TC)* | -65 to +150 deg C | 500 cycles | 24 lots | 0/1848 |
| Autoclave (AC)* | +121 deg C/ | • | | |
| | 15psig/100%RH | 96hrs | 12 lots | 0/924 |
| Temp. Humidity bias | | | | |
| (THB)* | +85 deg C/85%RH | 1008hrs | 9 lots | 0/693 |
| Power Temp Cycle | _ | | | |
| (PTC) | -40 to +125 deg C | 1000 cycles | 1 lot | 0/77 |
| Wire Bond Pull | _ | • | | |
| Strength (BPS)* | After TC, 30 bonds | | | |
| - , , | /5 units | 500 cycles | 12 lots | 0/60 |
| Wire Bond Shear | | • | | |
| Strength (BS) | 30 bonds/5 units | N/A | 1 lot | 0/5 |

^{*}Note: These tests may be performed with preconditioned parts depending upon the device type used.

In addition to the above tests, each qualification vehicle was subjected to the following tests in comparison to units manufactured at EG:

| Test | Conditions | Duration | Lots | Results |
|------------------|------------------|----------|--------------|------------|
| ESD testing | Human Body Model | N/A | 1 lot/device | Equivalent |
| | Machine Model | N/A | 1 lot/device | Equivalent |
| Dynamic Latch Up | 6 units per lot | N/A | 1 lot/device | Equivalent |

The temperature electrical characterization for each device showed no issue.

ELECTRICAL CHARACTERISTIC SUMMARY:

The temperature electrical characterization for each device showed no issue. Device parameters will continue to meet all datasheet specifications. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

There will be no changes to standard device markings. Normal assembly lots traceability codes will identify the wafer fab source. Products shipped after the expiration date of this notice may be sourced with die produced in the Roznov facility.

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AFFECTED DEVICE LIST (WITHOUT SPECIALS)

PART

CS5124XD8

CS5124XD8G

CS5124XDR8

CS5124XDR8G

CS8161YT5

CS8161YTHA5

CS8161YTHA5G

CS8161YTVA5

CS8161YTVA5G

CS9025DWR18G

NCV4279CD1

NCV4279CD1G

NCV4279CD1R2

NCV4279CD1R2G

NCV4279CD2

NCV4279CD2G

NCV4279CD2R2

NCV4279CD2R2G

NCV8509PDW18

NCV8509PDW18G

NCV8509PDW18R2

NCV8509PDW18R2G

NCV8509PDW25

NCV8509PDW25G

NCV8509PDW25R2

NCV8509PDW25R2G

NCV8509PDW26

NCV8509PDW26G

NCV8509PDW26R2

NCV8509PDW26R2G

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